

SKKT 107B16 E



Thyristor Modules

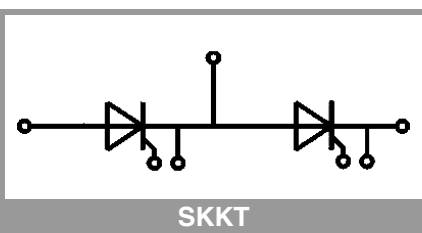
SKKT 107B16 E

Features

- Heat transfer through aluminium oxide ceramic isolated metal baseplate
- UL recognized, file no. E63532

Typical Applications*

- DC motor control (e. g. for machine tools)
- AC motor soft starters
- Temperature control (e. g. for ovens, chemical processes)
- Professional light dimming (studios, theaters)



Absolute Maximum Ratings				
Symbol	Conditions		Values	Unit
Chip				
I _{T(AV)}	sinus 180°	T _c = 85 °C	119	A
		T _c = 100 °C	91	A
I _{TRMS}	continuous operation		190	A
I _{TSM}	10 ms	T _j = 25 °C	2250	A
		T _j = 130 °C	1900	A
i ² t	10 ms	T _j = 25 °C	25313	A ² s
		T _j = 130 °C	18050	A ² s
V _{RSM}			1700	V
V _{RRM}			1600	V
V _{DRM}			1600	V
(di/dt) _{cr}	T _j = 130 °C		140	A/μs
(dv/dt) _{cr}	T _j = 130 °C		1000	V/μs
T _j			-40 ... 130	°C
Module				
T _{stg}			-40 ... 125	°C
V _{isol}	a.c.; 50 Hz; r.m.s.	1 min	3000	V
		1 s	3600	V

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Chip						
V _T	T _j = 25 °C, I _T = 300 A			1.6	1.75	V
V _{T(TO)}	T _j = 130 °C			0.8	0.9	V
r _T	T _j = 130 °C			2.80	3.35	mΩ
I _{DD} ; I _{RD}	T _j = 130 °C, V _{DD} = V _{DRM} ; V _{RD} = V _{RRM}				20	mA
t _{gd}	T _j = 25 °C, I _G = 1 A, di _G /dt = 1 A/μs			1		μs
t _{gr}	V _D = 0.67 * V _{DRM}			2		μs
t _q	T _j = 130 °C			200		μs
I _H	T _j = 25 °C			150	250	mA
I _L	T _j = 25 °C, R _G = 33 Ω			300	600	mA
V _{GT}	T _j = 25 °C, d.c.		2.5			V
I _{GT}	T _j = 25 °C, d.c.		100			mA
V _{GD}	T _j = 130 °C, d.c.				0.25	V
I _{GD}	T _j = 130 °C, d.c.				4	mA
R _{th(j-c)}	continuous DC	per chip			0.19	K/W
		per module			0.095	K/W
R _{th(j-c)}	sin. 180°	per chip			0.2	K/W
		per module			0.1	K/W
R _{th(j-c)}	rec. 120°	per chip			0.21	K/W
		per module			0.105	K/W
Module						
R _{th(c-s)}	chip			0.22		K/W
	module			0.11		K/W
M _s	to heatsink M5		4.25		5.75	Nm
M _t	to terminals M5		2.55		3.45	Nm
a					5 * 9,81	m/s ²
w				75		g

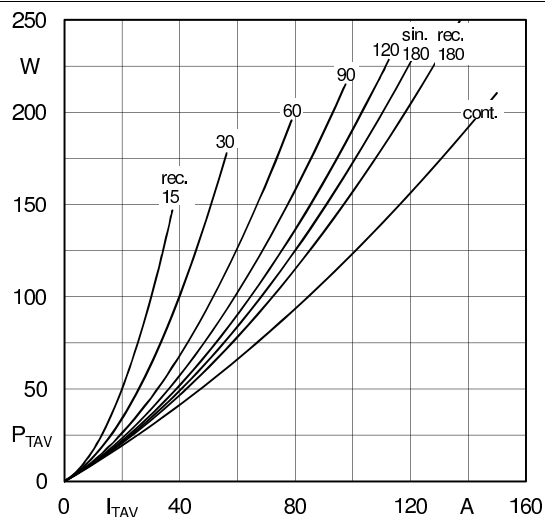


Fig. 1L: Power dissipation per thyristor/diode vs. on-state current

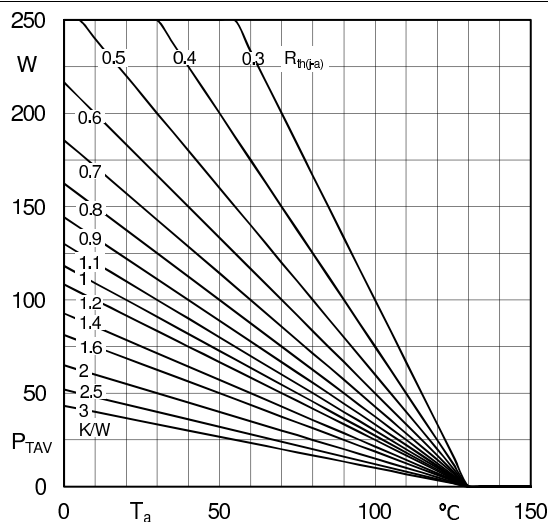


Fig. 1R: Max. power dissipation per chip vs. ambient temperature

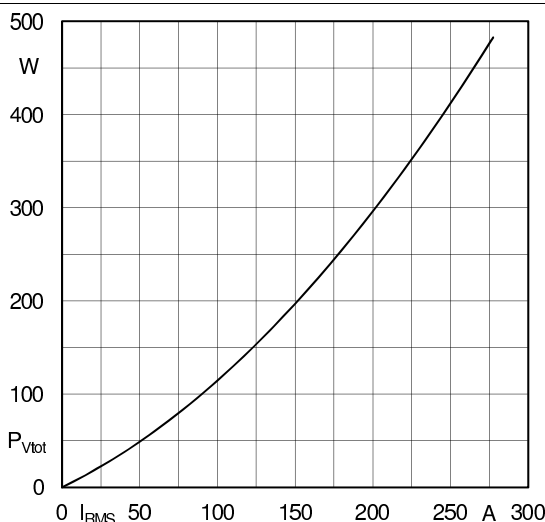


Fig. 2L: Max. power dissipation of one module vs. rms current

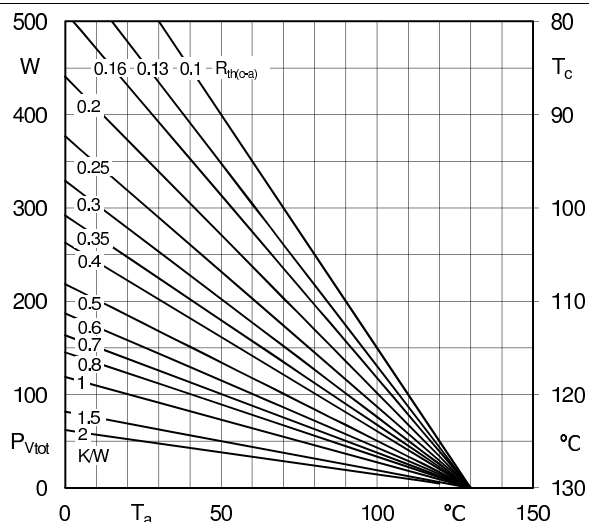


Fig. 2R: Max. power dissipation of one module vs. case temperature

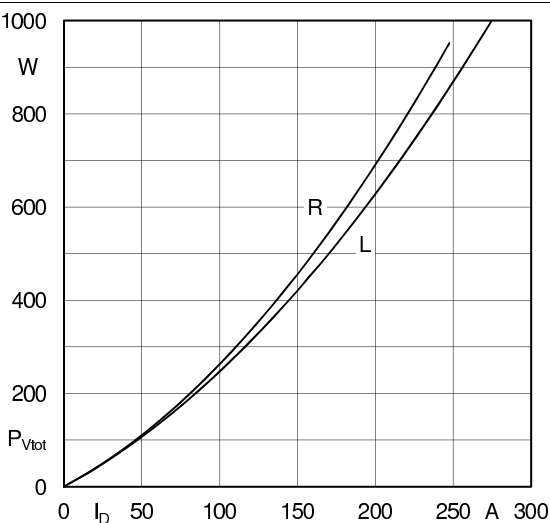


Fig. 3L: Max. power dissipation of two modules vs. direct current

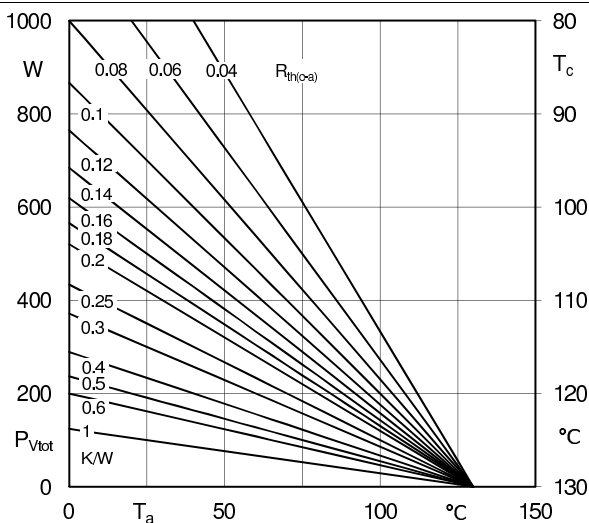


Fig. 3R: Max. power dissipation of two modules vs. case temperature

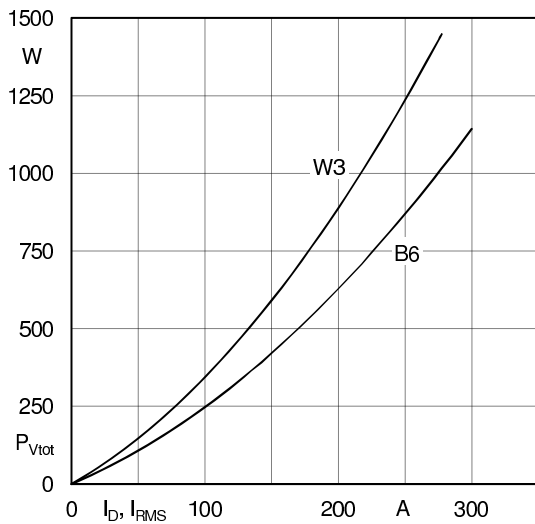


Fig. 4L: Max. power dissipation of three modules vs. direct current

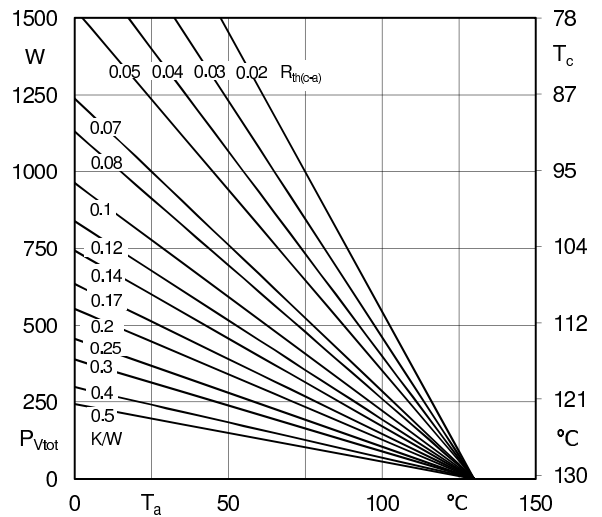


Fig. 4R: Max. power dissipation of three modules vs. case temperature

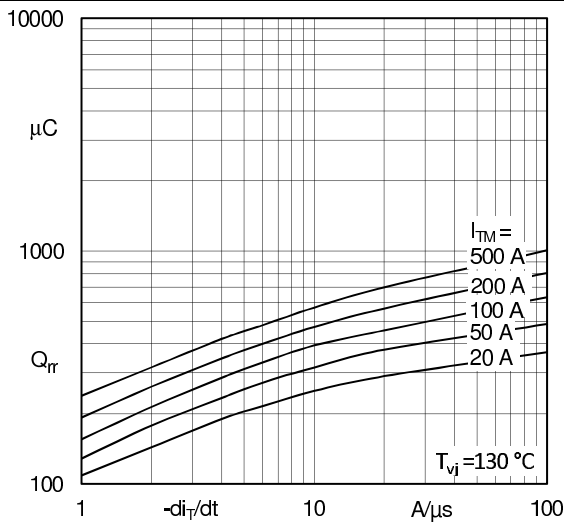


Fig. 5: Recovered charge vs. current decrease

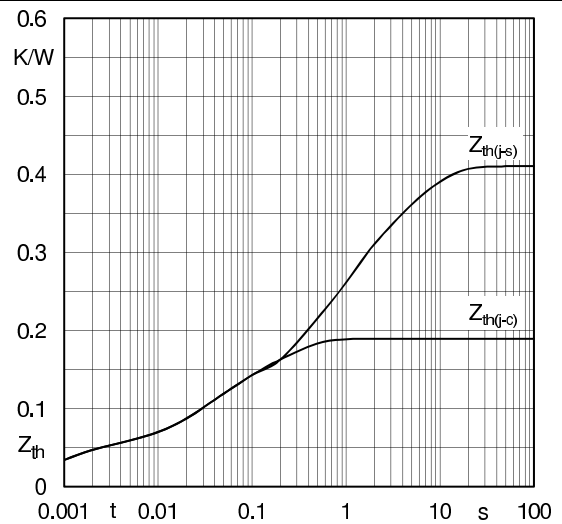


Fig. 6: Transient thermal impedance vs. time

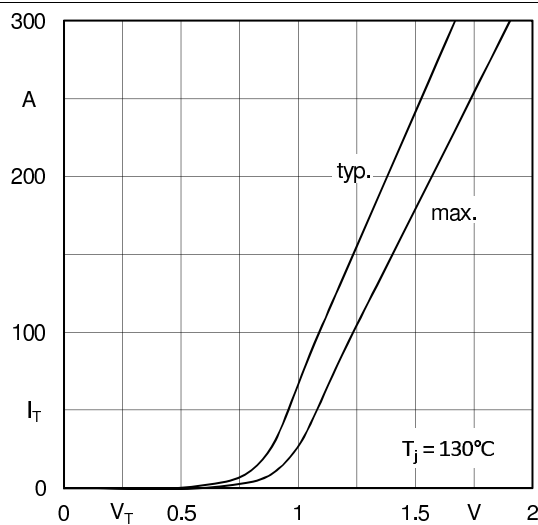


Fig. 7: On-state characteristics

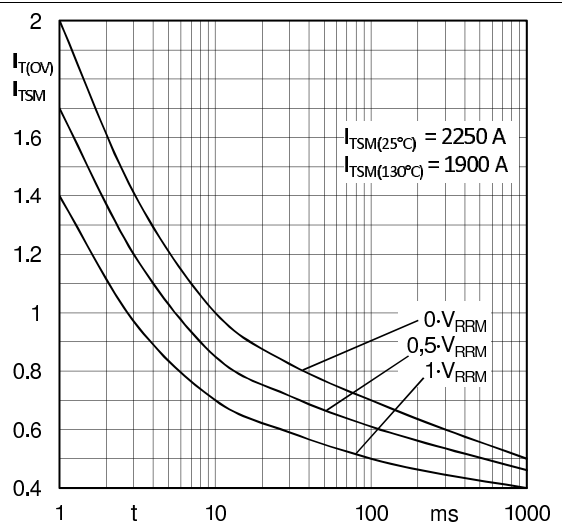


Fig. 8: Surge overload current vs. time

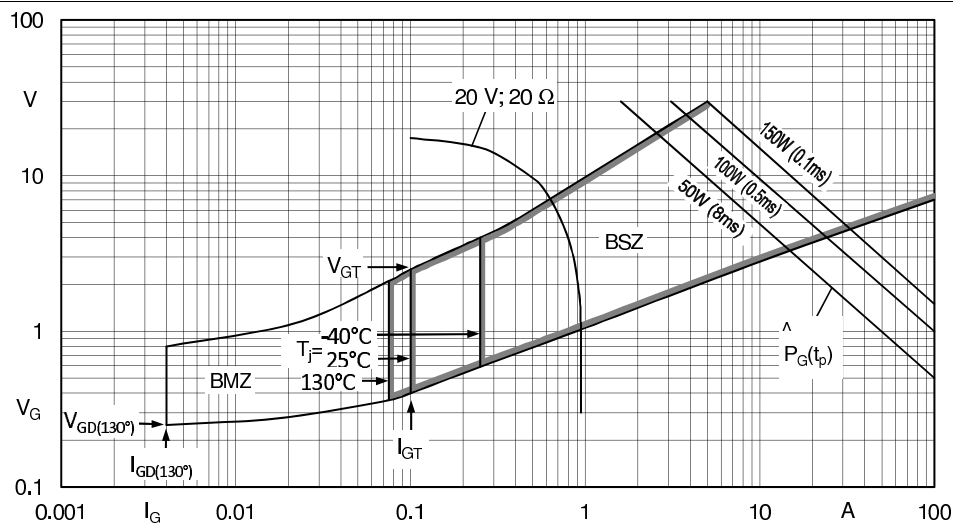
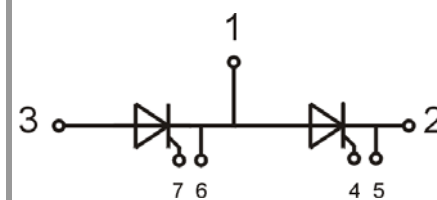
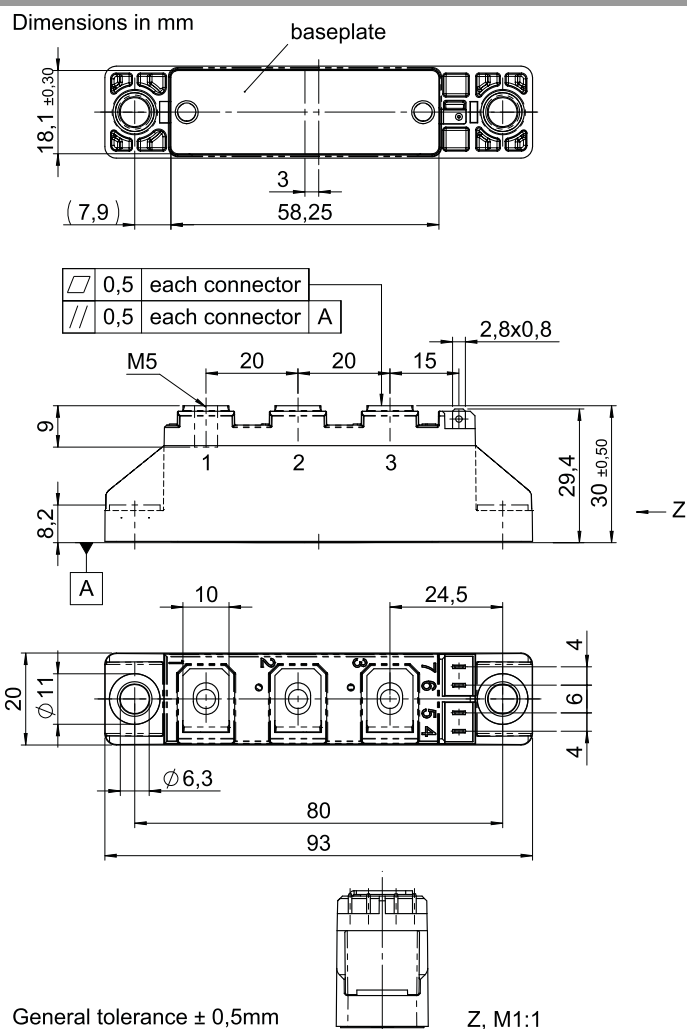


Fig. 9: Gate trigger characteristics



SKKT...B

SEMIACK 1

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

*IMPORTANT INFORMATION AND WARNINGS

The specifications of SEMIKRON products may not be considered as guarantee or assurance of product characteristics ("Beschaffenheitsgarantie"). The specifications of SEMIKRON products describe only the usual characteristics of products to be expected in

typical applications, which may still vary depending on the specific application. Therefore, products must be tested for the respective application in advance. Application adjustments may be necessary. The user of SEMIKRON products is responsible for the safety of their applications embedding SEMIKRON products and must take adequate safety measures to prevent the applications from causing a physical injury, fire or other problem if any of SEMIKRON products become faulty. The user is responsible to make sure that the application design is compliant with all applicable laws, regulations, norms and standards. Except as otherwise explicitly approved by SEMIKRON in a written document signed by authorized representatives of SEMIKRON, SEMIKRON products may not be used in any applications where a failure of the product or any consequences of the use thereof can reasonably be expected to result in personal injury. No representation or warranty is given and no liability is assumed with respect to the accuracy, completeness and/or use of any information herein, including without limitation, warranties of non-infringement of intellectual property rights of any third party. SEMIKRON does not assume any liability arising out of the applications or use of any product; neither does it convey any license under its patent rights, copyrights, trade secrets or other intellectual property rights, nor the rights of others. SEMIKRON makes no representation or warranty of non-infringement or alleged non-infringement of intellectual property rights of any third party which may arise from applications. Due to technical requirements our products may contain dangerous substances. For information on the types in question please contact the nearest SEMIKRON sales office. This document supersedes and replaces all information previously supplied and may be superseded by updates. SEMIKRON reserves the right to make changes.